**TRANSMITTAL OF FORMAL DRAWINGS**Docket No.  
SLA0493

In Re Application Of: Wei Pan, Jer-shen Maa, David R. Evans &amp; Sheng Teng Hsu

Serial No.	Filing Date	Batch No.	Examiner	Art Unit
09/820,068	03/28/2001		Bradley Smith	2824

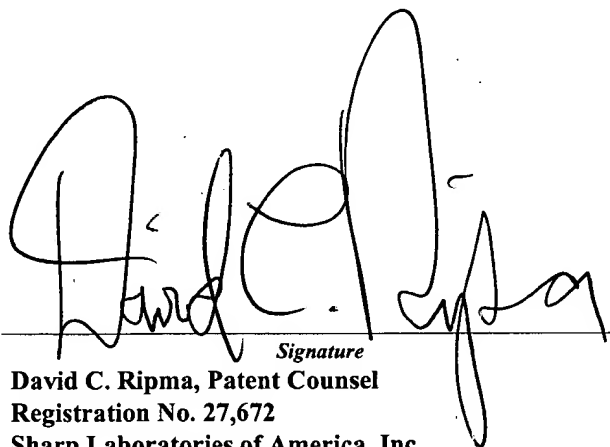
Invention: **Method of Barrier Metal Surface Treatment Prior to Cu Deposition to Improve Adhesion and Trench Filling Characteristics**

Address to:  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Transmitted herewith are:

2 sheets of formal drawing(s) for this application.

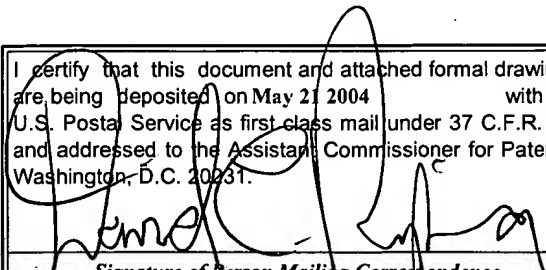
Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c) on the reverse side of the drawing.

  
Signature

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Dated: May 21, 2004

I certify that this document and attached formal drawings are being deposited on May 21, 2004 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

  
Signature of Person Mailing Correspondence  
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